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# Flexible and enhanced thermal conductivity of Al<sub>2</sub>O<sub>3</sub>@Polyimide hybrid film *via* coaxial electrospinning

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A novel core-shell structure of  $Al_2O_3$  nanoparticles (NPs) attached on poly (amic acid) (PAA) fiber has been successfully developed by facile coaxial electrospinning technology for the first time. The as-prepared PAA fiber went through imidization to prepare  $Al_2O_3$ @polyimide ( $Al_2O_3$ @PI) film. The resultant films with different  $Al_2O_3$  contents are characterized by scanning electron microscopy, Fourier transform infrared spectroscopy, thermal gravimetric analysis, and dynamical mechanical analysis, respectively. The results indicated that the  $Al_2O_3$  NPs could uniformly coat the surface of fibers with a diameter of about 1 µm which enhanced thermal and mechanical properties of fiber-based film. Especially for the flexible film with the content of  $Al_2O_3$  as high as 59.3 wt%, it present a high storage modulus (2.11GPa) and excellent thermal stability (474 °C at 5% mass loss) as well as superior thermal conductivity of 9.66 Wm<sup>-1</sup>K<sup>-1</sup> in plane. At last, compared with pure PI film, the  $Al_2O_3$ @PI fiber-based film exhibits excellent thermal transfer ability in the light emitting diode packaging. Therefore, the novel  $Al_2O_3$ @PI fiber-based film with integrated properties of insulation, thermal conductivity and flexibility can be used for wearable electronics and power devices.

#### **Supporting information**

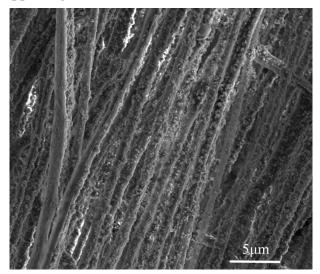
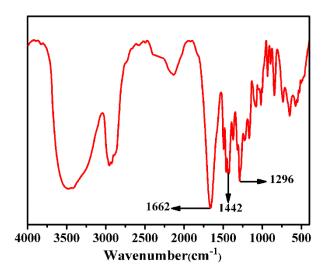
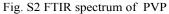


Fig. S1 SEM image of 74.5 wt% Al2O3@PAA with PVP





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Table S1 The thermal properties of composites with different contents of Al<sub>2</sub>O<sub>2</sub> NPs

of Al <sub>2</sub> O <sub>3</sub> NPs				
Al <sub>2</sub> O <sub>3</sub> (wt%)	Density (g·cm <sup>-3</sup> )	Heat capacity (J· K <sup>-1</sup> · g <sup>-1</sup> )	Thermal diffusion (mm <sup>2</sup> ·s <sup>-1</sup> )	Thermal conductivity (W·m <sup>-1</sup> ·k <sup>-1</sup> )
0	0.669	1.187	$4.789 \pm 0.544$	$3.80\pm0.43$
26.7	0.990	1.182	$4.834 \pm 0.626$	$5.66\pm0.73$
42.2	1.233	1.141	$5.107\pm0.330$	$7.18\pm0.46$
59.3	1.300	1.062	$7.000\pm0.234$	$9.66\pm0.32$
74.5	1.492	0.916	$7.242\pm0.320$	$9.90\pm0.44$